



15th International Workshop on

CHARACTERIZATION AND MODELING OF MEMORY DEVICES

October 1-2, 2026 | Politecnico of Milano, Italy
Aula Rogers - Building n. 11 – ground floor

PROGRAMME

October, 1

Memory for AI

9.30 Registration

10.20 **Welcome**

10.30 **Alessio Spessot** (IMEC)

Logic CMOS innovation for Memory in the context of AI and 3D innovation

11.15 **Olivier Noblanc** (STMicroelectronics)

3D heterogeneous integration technology compatible with Phase Change Memories

11.50 **Francois Andrieu** (CEA-LETI)

Memory roadmap for edge AI applications

12.25 **Premio Cappelletti**

12.35 Lunch

Emerging memories

14.15 **Themis Prodromakis** (University of Edinburgh)

Bridging Lab and Fab: AI-Accelerated Characterization and Modeling of Emerging Memory Technologies

14.50 **Uwe Schroeder** (NamLab)

Advances and Challenges of Doped HfO₂-Based Ferroelectrics in Volatile and Nonvolatile DRAM Applications

15.25 **Omar Abou El Kheir** (University of Milano-Bicocca)

Computational Materials Science in the Era of AI: Atomistic Device-Scale Simulation of Phase Change Memories

16.00 **Davide Donadio** (UC Davis)

From Atoms to Transistors: ab initio Thermal Modeling of Electronic Devices

16.35 Coffee break

October, 2

Memory Technologies and Applications

9.45 **Gurtej Sandhu** (Micron)

Memory Innovations Empowering AI - Role of AI to Drive Chip Development

10.30 **Anna Frosi** (Alenia spazio)

Memory Chip Usage in Space Applications

11.05 Coffee break

11.35 **Athanasios Vasilopoulos** (IBM)

Simulating the Inference of Analog In-Memory Computing Systems

12.10 **Stephan Menzel** (FZ Julich)

Memristive Devices for Thermal Computing

12.45 **Pau Diazcuesta** (BSC)

Performance and Energy Benefits of MRDIMMs

13.20 Adjourn

13.30 Lunch

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